

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. – 57. (canceled)

58. (currently amended) A semiconductor device comprising:  
a seal member formed of an insulating resin;  
a tab whose back side is exposed-to from a mounting surface of the seal  
member, the tab having, on a surface thereof opposite to the back side, a  
semiconductor chip fixing area and wire connection areas;  
tab suspension leads contiguous to the tab;  
a plurality of leads disposed around and apart from the tab, whose back sides  
are exposed-to from the mounting surface of the seal member;  
a semiconductor chip positioned within the seal member and fixed through an  
adhesive onto the semiconductor chip fixing area in such a manner that a back side  
of the semiconductor chip is opposed to the semiconductor chip fixing area, the  
semiconductor chip has electrodes formed on a main surface of the semiconductor  
chip;  
electrically conductive wires for electrically connecting the electrodes of the  
semiconductor chip and surfaces of the leads and electrically connecting the  
electrodes on the semiconductor chip and the wire connection areas on the tab,

wherein the tab is formed larger than the semiconductor chip so that outer peripheral edges of the tab are positioned outside outer peripheral edges of the semiconductor chip, and

wherein the tab has first-sides side surfaces formed at under the semiconductor chip fixing area and second-sides side surfaces opposed to the first sides side surfaces, each second side surface being formed between the semiconductor chip fixing area and the wire connection areas.

59. (previously presented) A semiconductor device according to claim 58, wherein the adhesive is not applied to the wire connection area on the tab.

60. (previously presented) A semiconductor device according to claim 58, wherein a plating film is formed selectively on the wire connection areas of the tab and the surfaces of the leads, and the wires are connected onto the plating film.

61. (currently amended) A semiconductor device according to claim 58, wherein the tab is quadrangular and the first-sides side surfaces and the second sides side surfaces are formed selectively in a mutually independent manner along sides of the quadrangle.

62. (previously presented) A semiconductor device according to claim 58, wherein a width of the surface of the tab is larger than a width of the back side of the tab.

63. (new) A semiconductor device according to claim 58, wherein a plurality of grooves are formed in the tab; and

the first side surfaces and the second side surfaces are inner surfaces of each of the plurality of grooves.

64. (new) A semiconductor device according to claim 58, wherein the semiconductor device is a surface mounting device.

65. (new) A semiconductor device according to claim 58, wherein the back side of the tab and the back sides of the leads are in a same plane.

66. (new) A semiconductor device according to claim 58, wherein each of the tab suspension leads is disposed between two adjacent leads of the plurality of leads.

67. (new) A semiconductor device according to claim 58, wherein the semiconductor device is a Quad Flat Non-leaded type device.

68. (new) A semiconductor device according to claim 62, wherein the tab has a section which is in the shape of an inverted trapezoid, with the surface thereof having an area larger than that of the back side thereof.

69. (new) A semiconductor device according to claim 68, wherein a distance between an exposed end of the back side of the tab and an inner end of each of said

plurality of leads is greater than a distance between a tip of the surface of the tab outside the second side surfaces thereof and the inner end of each of said plurality of leads.

70. (new) A semiconductor device according to claim 58, wherein each of the plurality of leads has a groove formed in a surface portion thereof, beneath and in contact with the insulating resin of the seal member.